



Material Content Data Sheet



Sales Product Name		BDP 948 H6327		Issued		1. August 2018		
MA#		MA001216704						
Package		PG-SOT223-4-24		Weight*		107.31 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.011	0.01		103	
	noble metal	gold	7440-57-5	0.043	0.04		399	
	inorganic material	silicon	7440-21-3	0.522	0.49	0.54	4864	5366
leadframe	inorganic material	silicon	7440-21-3	0.009	0.01		79	
	non noble metal	titanium	7440-32-6	0.043	0.04		397	
	non noble metal	chromium	7440-47-3	0.128	0.12		1192	
	non noble metal	copper	7440-50-8	42.459	39.57	39.74	395662	397330
wire	non noble metal	copper	7440-50-8	0.123	0.11	0.11	1143	1143
encapsulation	organic material	carbon black	1333-86-4	0.620	0.58		5779	
	plastics	epoxy resin	-	9.302	8.67		86686	
	inorganic material	silicondioxide	60676-86-0	52.093	48.54	57.79	485444	577909
leadfinish	non noble metal	tin	7440-31-5	1.464	1.36	1.36	13642	13642
plating	noble metal	silver	7440-22-4	0.495	0.46	0.46	4610	4610
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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